

What is Claimed is:

1. A method for fabricating Surface Acoustic Wave filter packages, the method comprising the following steps of:

5 preparing a plurality of SAW filter chips and a package sheet, wherein the package sheet has an outline pattern of a predetermined width formed along outer peripheries of predetermined chip mounting areas and circular anti-bur holes formed at corners of the mounting areas to be mounted with the  
10 SAW filter chips;

mounting the SAW filter chips on the package sheet;

forming a protective layer on the SAW filter chips on the package sheet;

removing predetermined portions of the protective layer  
15 between the SAW filter chips to expose the outline pattern on the package sheet and predetermined portions of the package sheet between the SAW filter chips;

forming a metal shield layer on the SAW filter chips, the exposed portions of the package sheet and the outline pattern;

20 and

cutting the package sheet along predetermined cutting lines extended through the anti-but holes between the SAW filter chips to form a plurality of SAW filter packages.

25 2. The method for fabricating Surface Acoustic Wave

filter packages as set forth in claim 1, wherein the outline pattern is formed on the package sheet with a predetermined length corresponding to the outer peripheries of the SAW filter chips.

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3. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 1, wherein each of the anti-bur holes has a predetermined size to cover all adjacent corners of corresponding mounting areas.

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4. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 1, wherein the package sheet comprises at least two sheet layers.

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5. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 4, wherein the anti-bur holes are formed in at least one sheet layer of the at least two sheet layers, the one sheet layer having a surface for mounting the SAW filter chips.

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6. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 1, wherein the SAW filter chips are provided on undersides with bumps for mounting the SAW filter chips.

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7. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 1, wherein the protective layer comprises a photosensitive film.

5 8. The method for fabricating Surface Acoustic Wave filter packages as set forth in claim 7, wherein the step of removing predetermined portions of the protective layer is carried out by dry etching.

10 9. A package sheet for a Surface Acoustic Wave filter package comprising:

an outline pattern formed along outer peripheries of predetermined areas to be mounted with a plurality of SAW filter chips, the outline pattern being contacted with a metal shield  
15 layer formed on the SAW filter chips and a predetermined region of the package sheet; and

20 circular anti-bur holes covering corners of the chip mounting areas to be mounted with the SAW filter chips and intersected by cutting lines functioning as reference lines for cutting the sheet into a plurality of SAW filter packages.

10. The package sheet for a Surface Acoustic Wave filter package as set forth in claim 9, wherein the outline pattern is formed in the package sheet with a length corresponding to  
25 the outer peripheries of the SAW filter chips.

11. The package sheet for a Surface Acoustic Wave filter package as set forth in claim 9, wherein each of the anti-bur holes has a predetermined size to cover all adjacent corners of corresponding mounting areas.

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12. The package sheet for a Surface Acoustic Wave filter package as set forth in claim 9, wherein the package sheet comprises at least two sheet layers.

10       13. The package sheet for a Surface Acoustic Wave filter package as set forth in claim 12, wherein the anti-bur holes are formed in at least one sheet layer of the at least two sheet layers, the one sheet layer having a surface for mounting the SAW filter chips.

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14. A Surface Acoustic Wave filter fabricated according to the method as set forth in claim 1.

20       15. A Surface Acoustic Wave filter fabricated using the package sheet as set forth in claim 9.